

Ultrafast Rectifier, 2 A FRED Pt®

eSMP® Series



Cathode  Anode

SMF (DO-219AB)

FEATURES

- Ultrafast recovery time, reduced Q_{rr} , and soft recovery
- 175 °C maximum operating junction temperature
- For PCF CRM, snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

DESIGN SUPPORT TOOLS

[click logo to get started](#)

3D
Models
Available

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 A
V_R	600 V
V_F at I_F	0.95 V
t_{rr}	55 ns
T_J max.	175 °C
Package	SMF (DO-219AB)
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

State of the art ultrafast recovery rectifiers designed with optimized performance of forward voltage drop, ultrafast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in PFC, boost, lighting, in the AC/DC section of SMPS, freewheeling and clamp diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 135\text{ °C}^{(1)}$	2	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25\text{ °C}$, 6 ms square pulse	30	
Operating junction and storage temperature range	T_J, T_{Stg}		-55 to +175	°C

Note

⁽¹⁾ Device on PCB with 8 mm x 16 mm soldering lands

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	V_F	$I_F = 2\text{ A}$	-	1.10	1.35	
		$I_F = 2\text{ A}, T_J = 150\text{ °C}$	-	0.95	1.15	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	-	3	μA
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	20	100	
Junction capacitance	C_T	$V_R = 600\text{ V}$	-	5	-	pF

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1\text{ A}$, $dI_F/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	42	-	ns
		$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$	-	-	55	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	40	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	63	-	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^{\circ}\text{C}$	-	7.0	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	8.1	-	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	140	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	255	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-55	-	+175	$^{\circ}\text{C}$
Thermal resistance, junction to case	R_{thJC}	Device mounted on PCB with 8 mm x 16 mm soldering lands	-	-	15	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient	R_{thJA}	Device mounted on PCB with 2 mm x 3.5 mm soldering lands	-	-	130	$^{\circ}\text{C}/\text{W}$
Approximate weight			0.015			g
			0.0005			oz.
Marking device		Case style SMF (DO-219AB)	MPU			

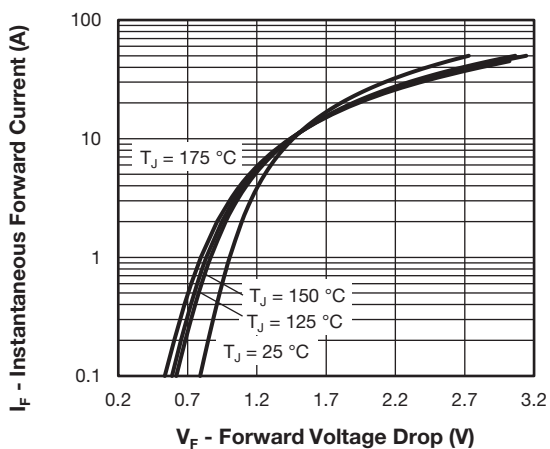


Fig. 1 - Typical Forward Voltage Drop Characteristics

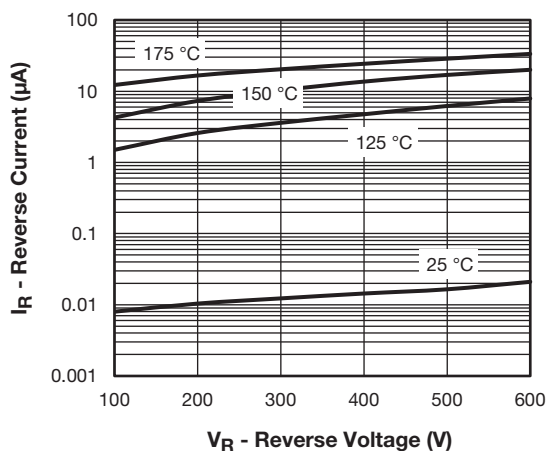


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

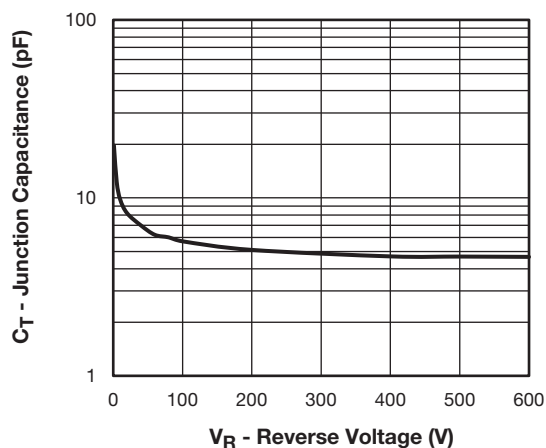


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

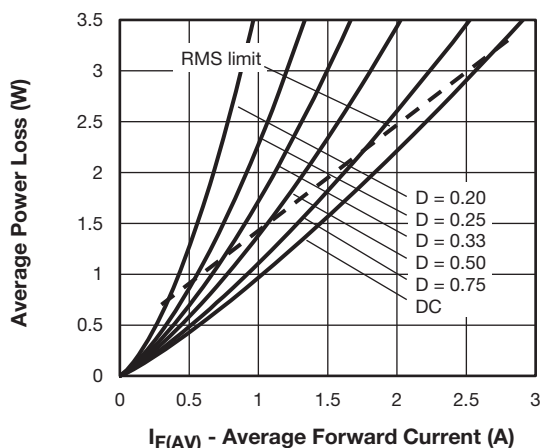


Fig. 5 - Forward Power Loss Characteristics

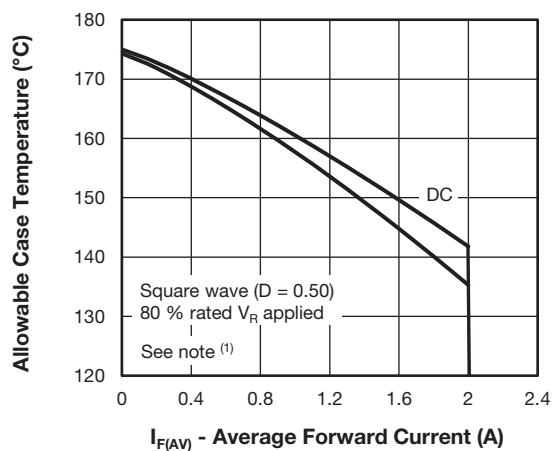
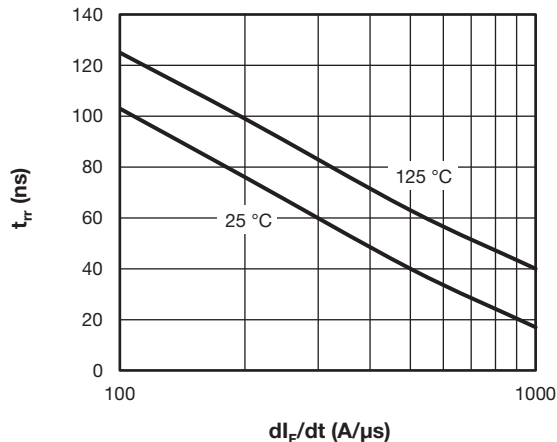
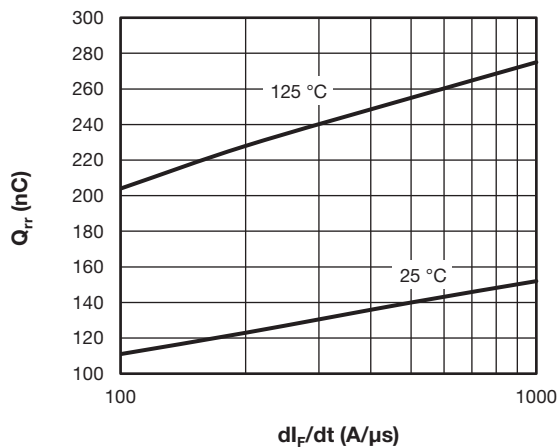


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current


Fig. 6 - Typical Reverse Recovery Time vs. dI_F/dt

Fig. 7 - Typical Stored Charge vs. dI_F/dt
Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5);
 P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

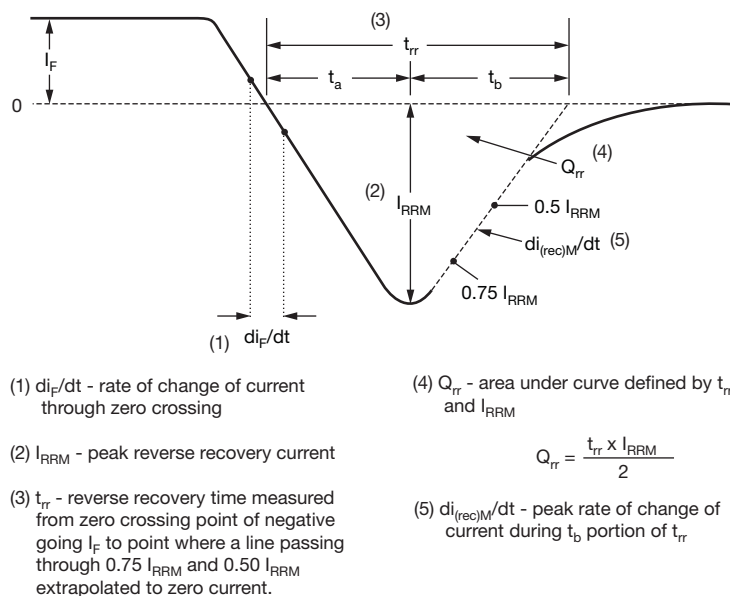


Fig. 8 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	VS-	2	E	F	U	06	H	M3
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - Current rating (2 = 2 A)
- 3** - Circuit configuration:
E = single diode
- 4** - F = SMF package
- 5** - Process type,
U = ultrafast recovery
- 6** - Voltage code (06 = 600 V)
- 7** - H = AEC-Q101 qualified
- 8** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-2EFU06HM3/I	10 000	10 000	13" diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95572
Part marking information	www.vishay.com/doc?95618
Packaging information	www.vishay.com/doc?95577



SMF (DO-219AB)

DIMENSIONS in millimeters (inches)



Foot print recommendation:



Created - Date: 15. February 2005
Rev. 3 - Date: 13. March 2007
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17247



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